



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

| | | | |
|---|---|--|---|
| PCN #: A0609-01 | DATE: 9/29/2006 | MEANS OF DISTINGUISHING CHANGED DEVICES: | |
| Product Affected: 655L, 24.5x19.5mm FCBGA (See attached affected part # list) | | <input type="checkbox"/> Product Mark | |
| Date Effective: 12/29/2006 | | <input type="checkbox"/> Back Mark | |
| | | <input type="checkbox"/> Date Code | |
| | | <input checked="" type="checkbox"/> Other | Lot # will have "SP" prefix |
| Contact: Bimla Paul | | Attachment: | <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No |
| Title: Product Quality Assurance | | Samples: | Please contact your local sales representative for sample request & availability. |
| Phone #: (408) 574-6419 | | | |
| Fax #: (408) 284-8362 | | | |
| E-mail: Bimla.Paul@idt.com | | | |
| DESCRIPTION AND PURPOSE OF CHANGE: | | | |
| <input type="checkbox"/> Die Technology | This notification is to advise our customers that IDT has added SPIL, Taiwan as an alternate Assembly facility for 655L, 24.5x19.5mm FCBGA package. There is no change to the moisture performance of the package as a result of this change. | | |
| <input type="checkbox"/> Wafer Fabrication Process | | | |
| <input type="checkbox"/> Assembly Process | | | |
| <input type="checkbox"/> Equipment | | | |
| <input type="checkbox"/> Material | | | |
| <input type="checkbox"/> Testing | | | |
| <input checked="" type="checkbox"/> Manufacturing Site | Please see attached for the qualification data and affected part number list. | | |
| <input type="checkbox"/> Data Sheet | | | |
| <input type="checkbox"/> Other | | | |
| RELIABILITY/QUALIFICATION SUMMARY: | | | |
| Please refer to the attached Qualification & Reliability data. | | | |
| CUSTOMER ACKNOWLEDGMENT OF RECEIPT: | | | |
| IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted. | | | |
| Customer: _____ | <input type="checkbox"/> | <i>Approval for shipments prior to effective date.</i> | |
| Name/Date: _____ | E-Mail Address: | _____ | |
| Title: _____ | Phone# /Fax# : | _____ | |
| CUSTOMER COMMENTS: _____ _____ _____ | | | |
| IDT ACKNOWLEDGMENT OF RECEIPT: | | | |
| RECD. BY: _____ | DATE: | _____ | |



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ATTACHMENT I - PCN # : A0609-01

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT has added SPIL, Taiwan as an alternate Assembly facility for 655L, 24.5x19.5mm FCBGA package. The assembly material set for SPIL assembly location is listed in Table 1.

There is no change in the moisture sensitivity level (MSL) as a result of this change.

Attachment I outlines the qualification data and affected part#s.

Table 1

| Description | Existing | Add |
|-------------------|--|---|
| Assembly Location | AMKOR Philippines, Korea and Taiwan, STATSChipPAC, Korea | SPIL, Taiwan |
| Assembly Material | 95Pb/5Sn (High Pb Bump), NAU6 or CRP-4152RA (Underfill), TTG3 (Thermal Grease), 96.5Sn/3Ag/0.5Cu (Solder Ball) | 95Pb/5Sn (High Pb Bump), U8439-1 (Underfill), TTG3 (Thermal Grease), 96.5Sn/3Ag/0.5Cu (Solder Ball) |

Sample Availability:

Samples are already available for customer evaluation.

Please contact your local IDT sales representative for your sample request and availability.



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ATTACHMENT I - PCN # : A0609-01

Qualification Information and Qualification Tests Result:

Test Vehicles: 31 x31 mm FCBGA, 740 balls (1 assembly lot)

| Test Description | Test Method | Test Results (SS/ Rej) |
|--|-------------|------------------------|
| * Temperature Cycling (-40°C to +125°C, 1000 cycles) | JESD22-A104 | 45/0 |
| * HAST (110°C / 85% RH, 264 hours) | JESD22-A110 | 45/0 |
| High Temperature Stabilization Bake (150 °C, 1000 hours) | JESD22-A103 | 45/0 |
| Moisture Sensitivity Classification, L4 | J-STD-020 | 90/0 |

Notes: * Test requires moisture pre-conditioning sequence per JESD22-A113.

Affected Part #s

IDTAMB0480A5RH

IDTAMB0480A5RJ